



## Description

The FDD6685 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



TO-252-2L

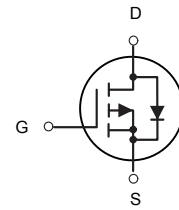
## General Features

$V_{DS} = -30V$   $I_D = 50A$

$R_{DS(ON)} < 18m\Omega @ V_{GS}=10V$

## Application

Battery protection  
Load switch  
Uninterruptible power supply



P-Channel MOSFET

## Package Marking and Ordering Information

| Product ID | Pack      | Brand      | Qty(PCS) |
|------------|-----------|------------|----------|
| FDD6685    | TO-252-2L | HXY MOSFET | 2500     |

## Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise noted)

| Symbol                      | Parameter  | Rating     | Units              |
|-----------------------------|--|------------|--------------------|
| $V_{DS}$                    | Drain-Source Voltage                             | -30        | V                  |
| $V_{GS}$                    | Gate-Source Voltage                              | $\pm 25$   | V                  |
| $I_D@T_C=25^\circ\text{C}$  | Continuous Drain Current, $V_{GS} @ -10V^1$      | -50        | A                  |
| $I_D@T_C=100^\circ\text{C}$ | Continuous Drain Current, $V_{GS} @ -10V^1$      | -32        | A                  |
| $I_D@T_A=25^\circ\text{C}$  | Continuous Drain Current, $V_{GS} @ -10V^1$      | -9.6       | A                  |
| $I_D@T_A=70^\circ\text{C}$  | Continuous Drain Current, $V_{GS} @ -10V^1$      | -7.7       | A                  |
| $I_{DM}$                    | Pulsed Drain Current <sup>2</sup>                | -150       | A                  |
| EAS                         | Single Pulse Avalanche Energy <sup>3</sup>       | 125        | mJ                 |
| $I_{AS}$                    | Avalanche Current                                | -50        | A                  |
| $P_D@T_C=25^\circ\text{C}$  | Total Power Dissipation <sup>4</sup>             | 45         | W                  |
| $P_D@T_A=25^\circ\text{C}$  | Total Power Dissipation <sup>4</sup>             | 2          | W                  |
| $T_{STG}$                   | Storage Temperature Range                        | -55 to 150 | $^\circ\text{C}$   |
| $T_J$                       | Operating Junction Temperature Range             | -55 to 150 | $^\circ\text{C}$   |
| $R_{\theta JA}$             | Thermal Resistance Junction-Ambient <sup>1</sup> | 62         | $^\circ\text{C/W}$ |
| $R_{\theta JC}$             | Thermal Resistance Junction-Case <sup>1</sup>    | 2.8        | $^\circ\text{C/W}$ |



**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

| Symbol                 | Parameter                                      | Conditions   | Min. | Typ.    | Max. | Unit  |
|------------------------|--|--|------|---------|------|-------|
| BV <sub>DSS</sub>      | Drain-Source Breakdown Voltage                 | V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA  | -30  | ---     | ---  | V     |
| ΔBV <sub>DSS</sub> /ΔT | BVDSS Temperature Coefficient                  | Reference to 25°C, I <sub>D</sub> =-1mA  | ---  | -0.0232 | ---  | V/°C  |
| R <sub>DS(ON)</sub>    | Static Drain-Source On-Resistance <sup>2</sup> | V <sub>GS</sub> =-10V, I <sub>D</sub> =-30A  | ---  | 15      | 18   | mΩ    |
|                        |  | V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-15A   | ---  | 24      | 32   |       |
| V <sub>GS(th)</sub>    | Gate Threshold Voltage                         | V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA                                  | -1.0 | ---     | -2.5 | V     |
| ΔV <sub>GS(th)</sub>   | V <sub>GS(th)</sub> Temperature Coefficient    |  | ---  | 4.6     | ---  | mV/°C |
| I <sub>DSS</sub>       | Drain-Source Leakage Current                   | V <sub>DS</sub> =-24V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C                           | ---  | ---     | -1   | uA    |
|                        |  | V <sub>DS</sub> =-24V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C                           | ---  | ---     | -5   |       |
| I <sub>GSS</sub>       | Gate-Source Leakage Current                    | V <sub>GS</sub> =±25V, V <sub>DS</sub> =0V   | ---  | ---     | ±100 | nA    |
| g <sub>fs</sub>        | Forward Transconductance                       | V <sub>DS</sub> =-5V, I <sub>D</sub> =-30A   | ---  | 30      | ---  | S     |
| R <sub>g</sub>         | Gate Resistance                                | V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz   | ---  | 9       | ---  | Ω     |
| Q <sub>g</sub>         | Total Gate Charge (-4.5V)                      | V <sub>DS</sub> =-15V, V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-15A                        | ---  | 22      | ---  | nC    |
| Q <sub>gs</sub>        | Gate-Source Charge                             |  | ---  | 8.7     | ---  |       |
| Q <sub>gd</sub>        | Gate-Drain Charge                              |  | ---  | 7.2     | ---  |       |
| T <sub>d(on)</sub>     | Turn-On Delay Time                             | V <sub>DD</sub> =-15V, V <sub>GS</sub> =-10V, R <sub>G</sub> =3.3Ω<br>I <sub>D</sub> =-15A | ---  | 8       | ---  | ns    |
| T <sub>r</sub>         | Rise Time                                      |  | ---  | 73.7    | ---  |       |
| T <sub>d(off)</sub>    | Turn-Off Delay Time                            |  | ---  | 61.8    | ---  |       |
| T <sub>f</sub>         | Fall Time                                      |  | ---  | 24.4    | ---  |       |
| C <sub>iss</sub>       | Input Capacitance                              | V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V, f=1MHz   | ---  | 2215    | ---  | pF    |
| C <sub>oss</sub>       | Output Capacitance                             |  | ---  | 310     | ---  |       |
| C <sub>rss</sub>       | Reverse Transfer Capacitance                   |  | ---  | 237     | ---  |       |
| I <sub>S</sub>         | Continuous Source Current <sup>1,5</sup>       | V <sub>G</sub> =V <sub>D</sub> =0V, Force Current  | ---  | ---     | -50  | A     |
| I <sub>SM</sub>        | Pulsed Source Current <sup>2,5</sup>           |  | ---  | ---     | -150 | A     |
| V <sub>SD</sub>        | Diode Forward Voltage <sup>2</sup>             | V <sub>GS</sub> =0V, I <sub>S</sub> =-1A, T <sub>J</sub> =25°C                             | ---  | ---     | -1   | V     |
| t <sub>rr</sub>        | Reverse Recovery Time                          | I <sub>F</sub> =-15A, dI/dt=100A/μs,   | ---  | 19      | ---  | nS    |
| Q <sub>rr</sub>        | Reverse Recovery Charge                        | T <sub>J</sub> =25°C   | ---  | 9       | ---  | nC    |

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
- 3.The EAS data shows Max. rating. The test condition is V<sub>DD</sub>=-25V, V<sub>GS</sub>=-10V, L=0.1mH, I<sub>AS</sub>=-50A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub>, in real applications, should be limited by total power dissipation.



### Typical Characteristics

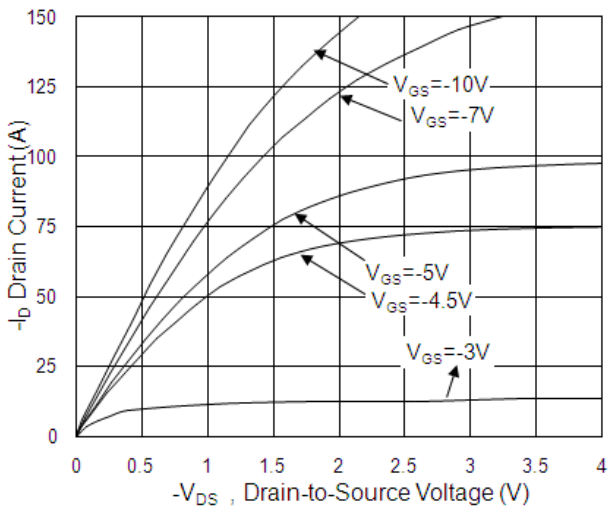


Fig.1 Typical Output Characteristics

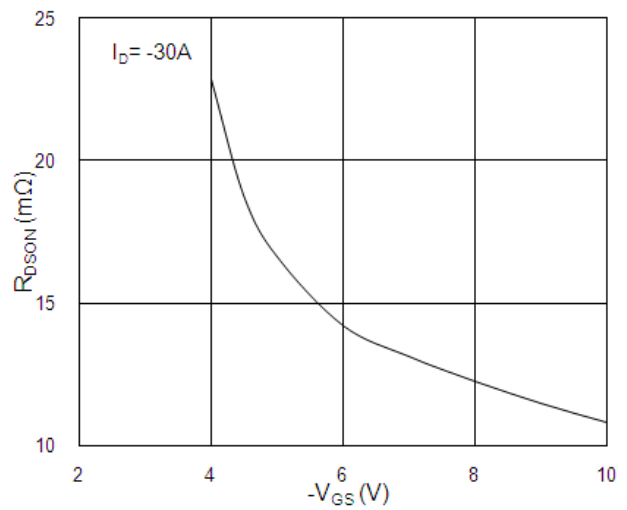


Fig.2 On-Resistance vs. G-S Voltage

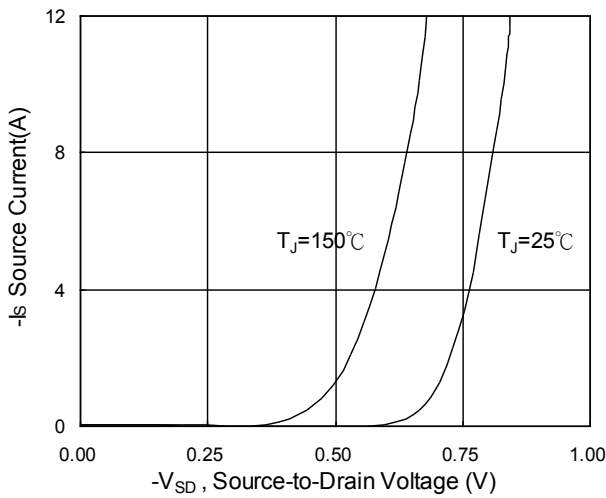


Fig.3 Forward Characteristics of Reverse

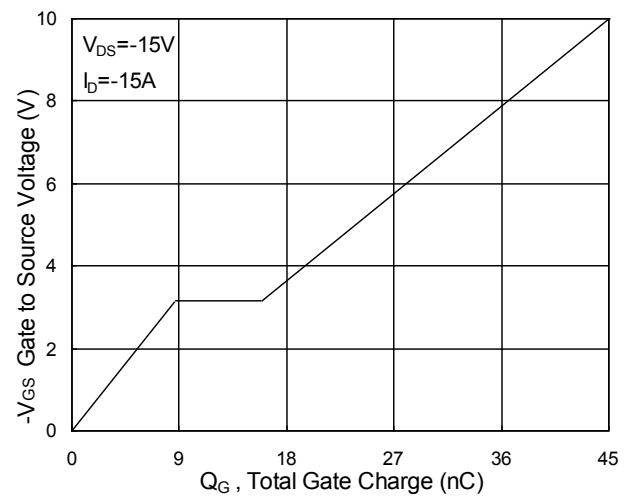


Fig.4 Gate-charge Characteristics

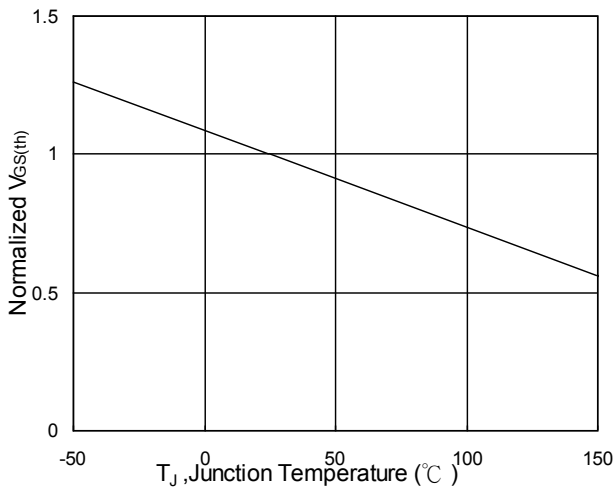


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

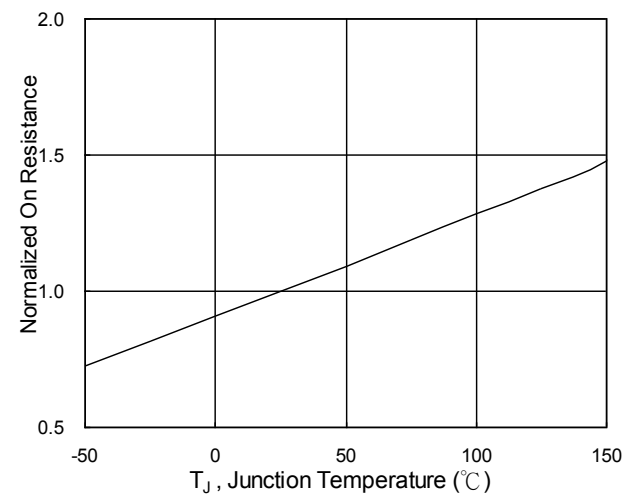


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

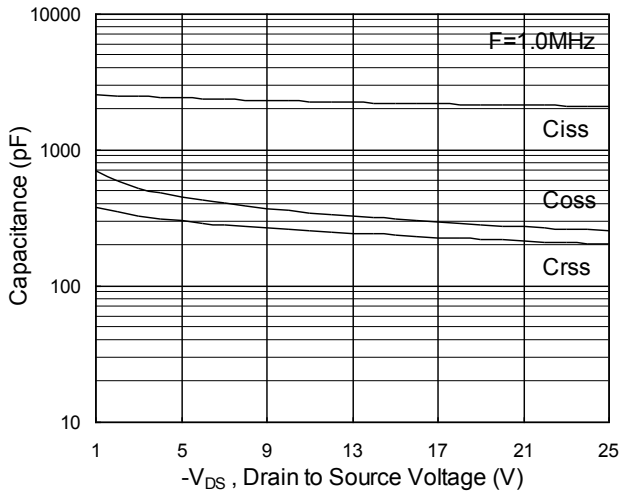


Fig.7 Capacitance

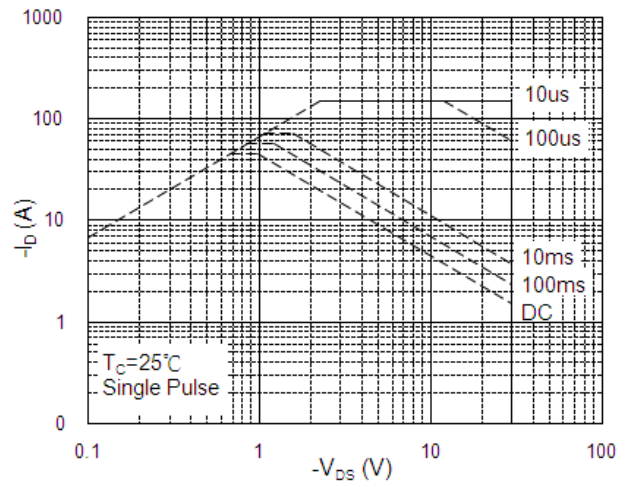


Fig.8 Safe Operating Area

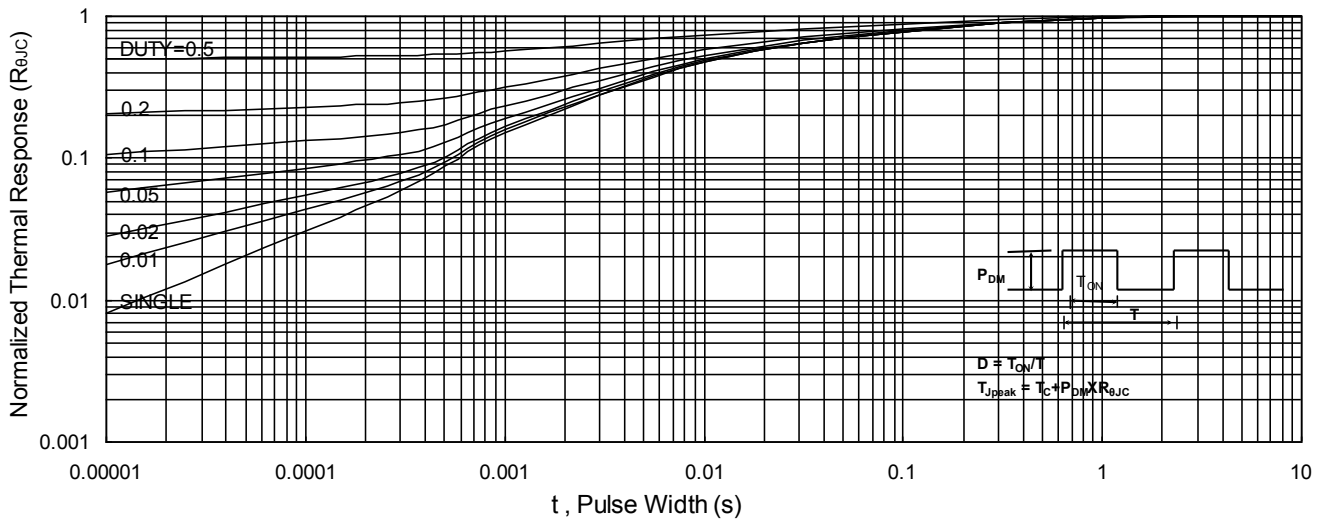


Fig.9 Normalized Maximum Transient Thermal Impedance

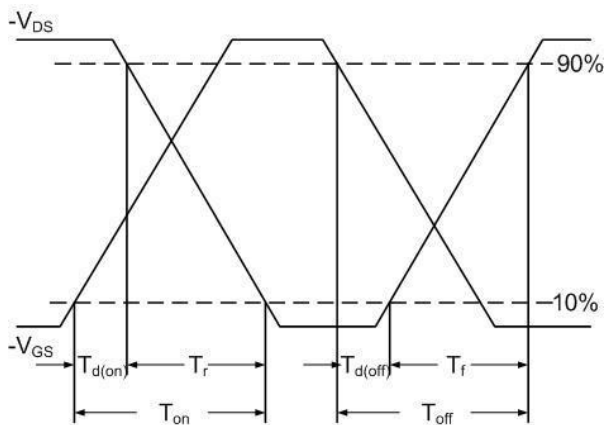


Fig.10 Switching Time Waveform

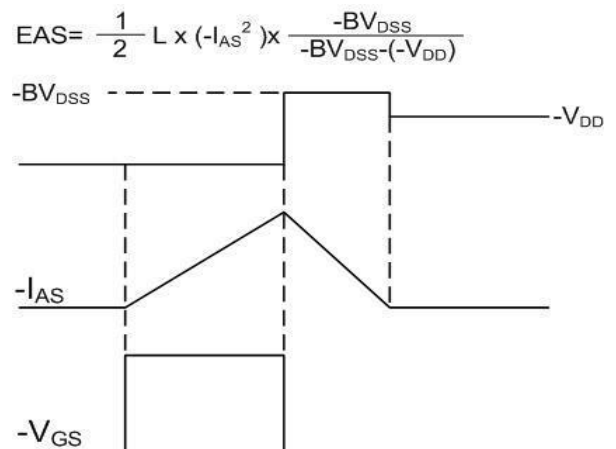
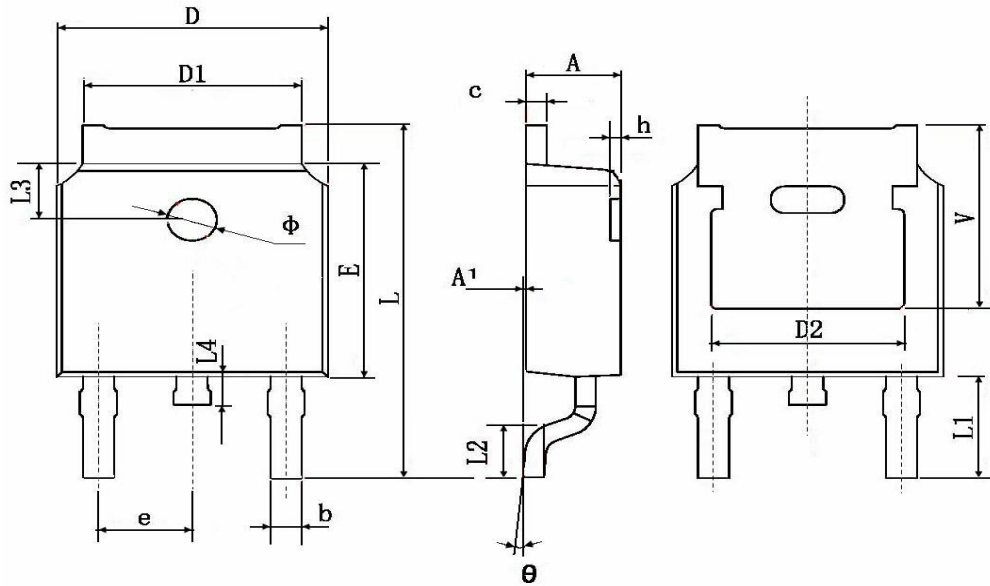


Fig.11 Unclamped Inductive Switching Waveform



### TO-252-2L Package Information



| Symbol | Dimensions In Millimeters |        | Dimensions In Inches |       |
|--------|---------------------------|--------|----------------------|-------|
|        | Min.                      | Max.   | Min.                 | Max.  |
| A      | 2.200                     | 2.400  | 0.087                | 0.094 |
| A1     | 0.000                     | 0.127  | 0.000                | 0.005 |
| b      | 0.660                     | 0.860  | 0.026                | 0.034 |
| c      | 0.460                     | 0.580  | 0.018                | 0.023 |
| D      | 6.500                     | 6.700  | 0.256                | 0.264 |
| D1     | 5.100                     | 5.460  | 0.201                | 0.215 |
| D2     | 4.830 TYP.                |        | 0.190 TYP.           |       |
| E      | 6.000                     | 6.200  | 0.236                | 0.244 |
| e      | 2.186                     | 2.386  | 0.086                | 0.094 |
| L      | 9.800                     | 10.400 | 0.386                | 0.409 |
| L1     | 2.900 TYP.                |        | 0.114 TYP.           |       |
| L2     | 1.400                     | 1.700  | 0.055                | 0.067 |
| L3     | 1.600 TYP.                |        | 0.063 TYP.           |       |
| L4     | 0.600                     | 1.000  | 0.024                | 0.039 |
| φ      | 1.100                     | 1.300  | 0.043                | 0.051 |
| θ      | 0°                        | 8°     | 0°                   | 8°    |
| h      | 0.000                     | 0.300  | 0.000                | 0.012 |
| V      | 5.350 TYP.                |        | 0.211 TYP.           |       |



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